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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





LDP24A

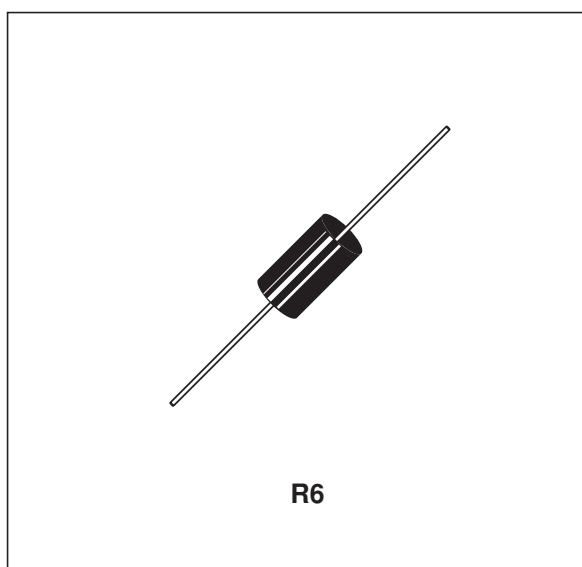
TRANSIENT PROTECTION LOAD DUMP

FEATURES

- TRANSIENT VOLTAGE SUPPRESSOR DIODE ESPECIALLY DESIGNED FOR LOAD DUMP PROTECTION
- COMPLIANT WITH MAIN STANDARDS SUCH AS:
ISO / DTR 7637

DESCRIPTION

Transient voltage suppressor diodes especially useful in protecting integrated circuits, MOS, hybrids and other overvoltages sensitive semiconductors and components.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{PP}	Peak pulse load dump overvoltage See note 1	$T_{amb} = 85^{\circ}C$	100	V
P	Power dissipation on infinite heatsink	$T_{amb} = 100^{\circ}C$	5	W
I_{FSM}	Non repetitive surge peak forward current.	T_j initial = $25^{\circ}C$ $t_p = 10$ ms	500	A
T_{stg}	Storage temperature range.		- 65 to + 175	$^{\circ}C$
T_j	Maximum operating temperature		175	$^{\circ}C$
T_L	Maximum lead temperature for soldering during 10 sec at 4 mm from case.		230	$^{\circ}C$

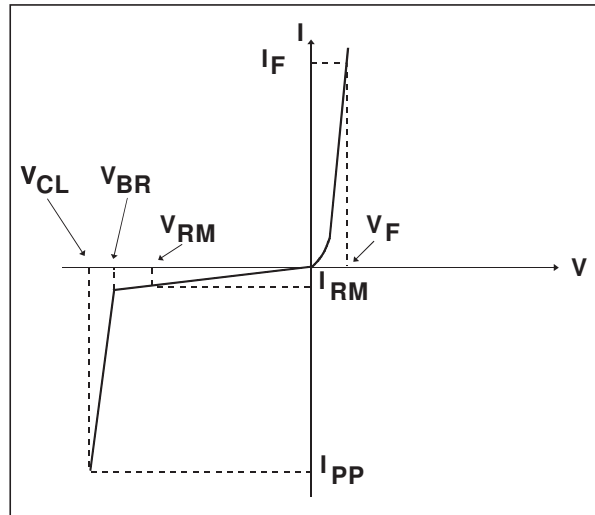
THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction ambient thermal resistance on infinite heatsink $L_{lead} = 10$ mm	15	$^{\circ}C/W$

Note 1: For surges greater than the maximum values, the diode will present a short-circuit Anode - Cathode.

ELECTRICAL CHARACTERISTICS

Symbol	Parameter
V_{RM}	Stand-off voltage.
V_{BR}	Breakdown voltage.
V_{CL}	Clamping voltage.
I_{PP}	Peak pulse current.
αT	Temperature coefficient of V_{BR} .
C	Capacitance
I_{RM}	Leakage current at V_{RM}
V_F	Peak forward voltage drop



Symbol	Test Conditions	Min.	Typ.	Max.	Unit
I_{pp}	Pulse duration: 40ms	30			A
I_{RM}	$T_j = 25^\circ C$ $T_j = 85^\circ C$ $V_{RM} = 24 V$ $V_{RM} = 24 V$			50 300	μA μA
V_{BR}	$T_j = 25^\circ C$ $I_R = 1mA$	25		32	V
V_{CL}	$T_j = 85^\circ C$ see table1			40	V
αT				10	$10^{-4}/^\circ C$
C	F = 1MHz $V_R = 0V$		8000		pF
V_F	$I_{FM} = 10A$		0.9		V

LOAD DUMP TEST GENERATOR CIRCUIT (SCHAFFNER NSG 506 C). Issued from ISO / DTR 7637.

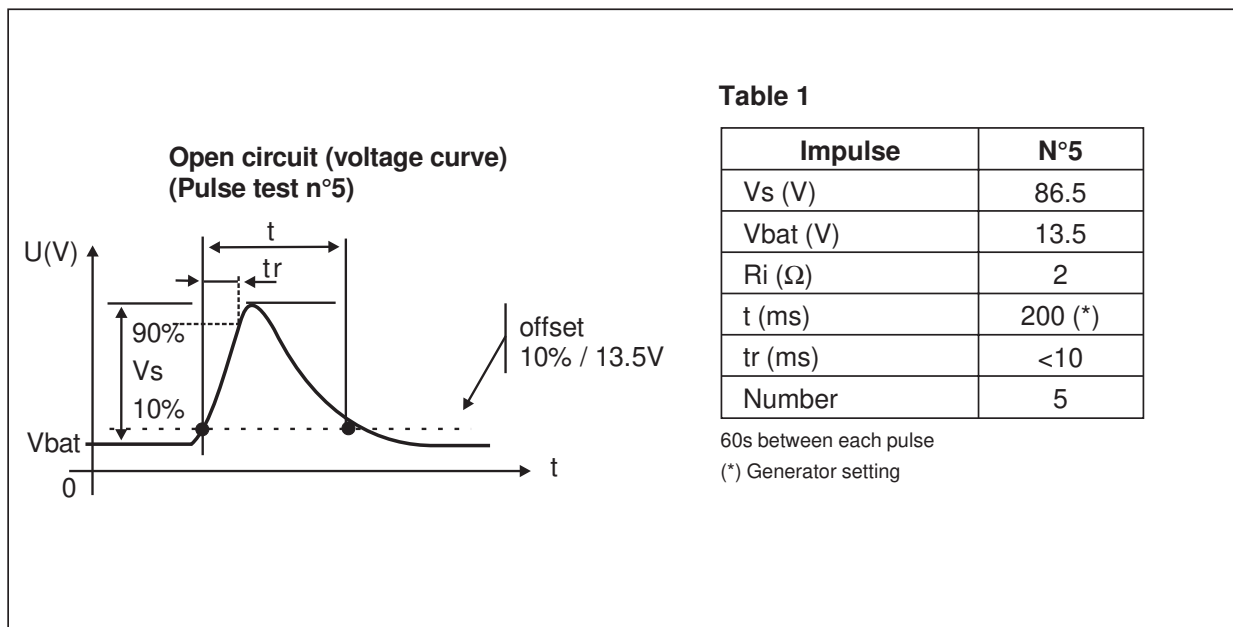


Fig. 1: Peak pulse power versus exponential pulse duration (T_j initial=85°C).

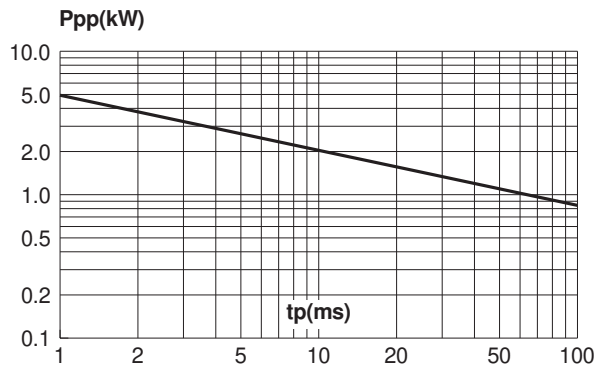


Fig. 2 : Peak pulse current versus exponential pulse duration (T_j initial=85°C).

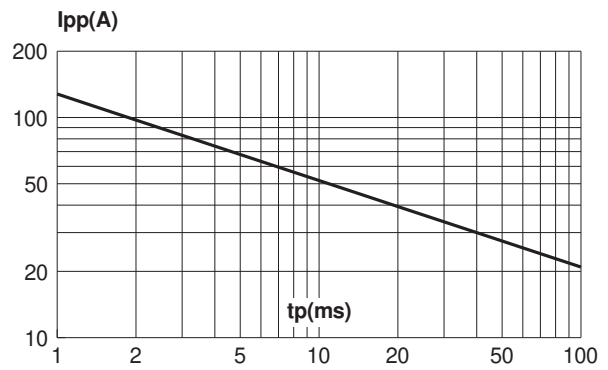


Fig. 3: Relative variation of peak pulse power versus junction temperature.

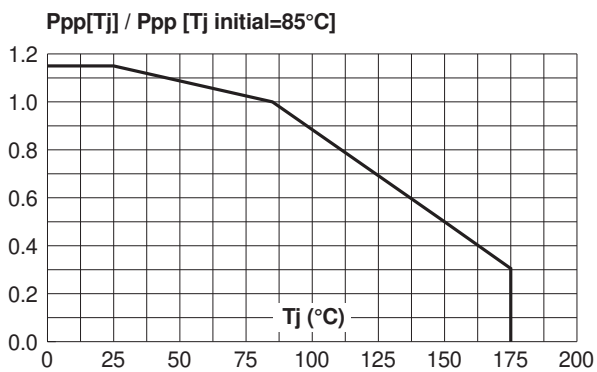


Fig. 4: Continuous power dissipation versus ambient temperature.

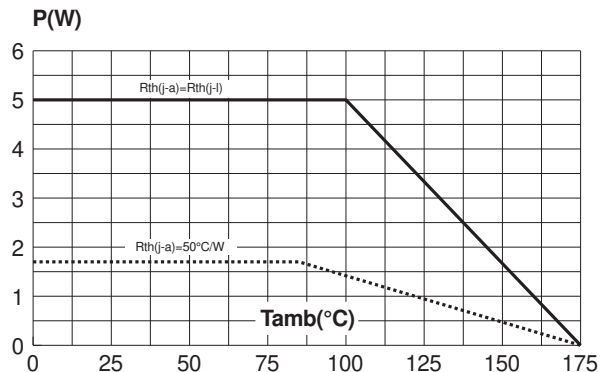


Fig. 5: Variation of thermal impedance junction to ambient versus pulse duration (printed circuit board FR4, $\epsilon(\text{Cu})=35\mu\text{m}$, $\text{SCu}=1\text{cm}^2$).

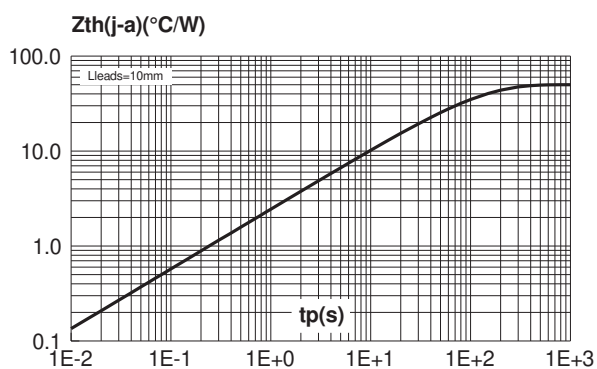
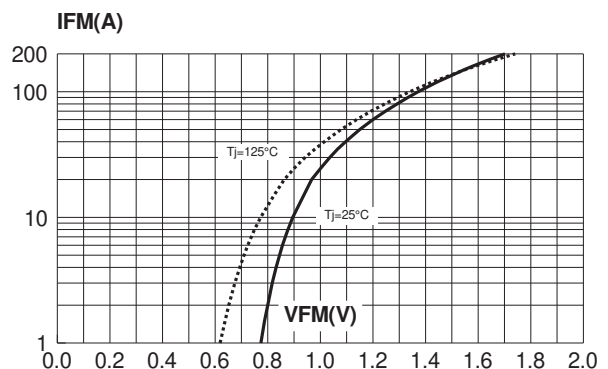


Fig. 6 : Peak forward voltage drop versus peak forward current (typical values).



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Fig. 7: Non repetitive surge peak forward current versus sinusoidal pulse duration and corresponding value of I^2t .

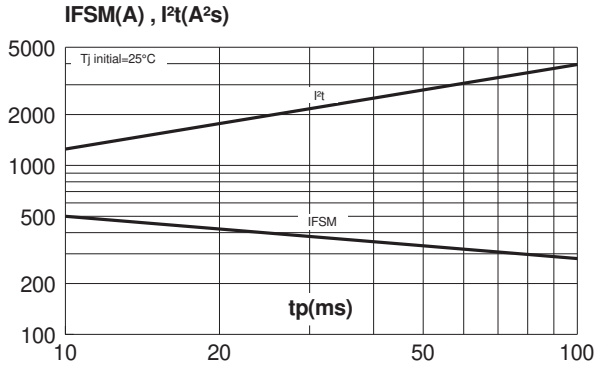
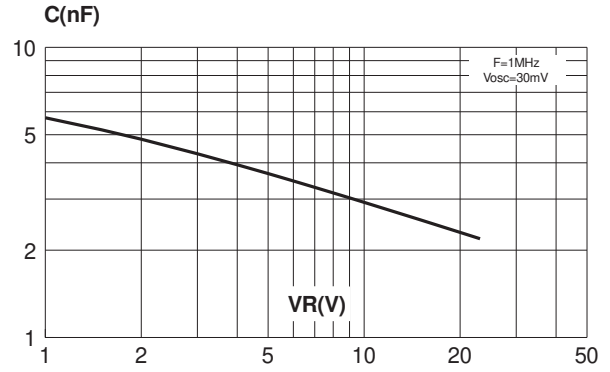
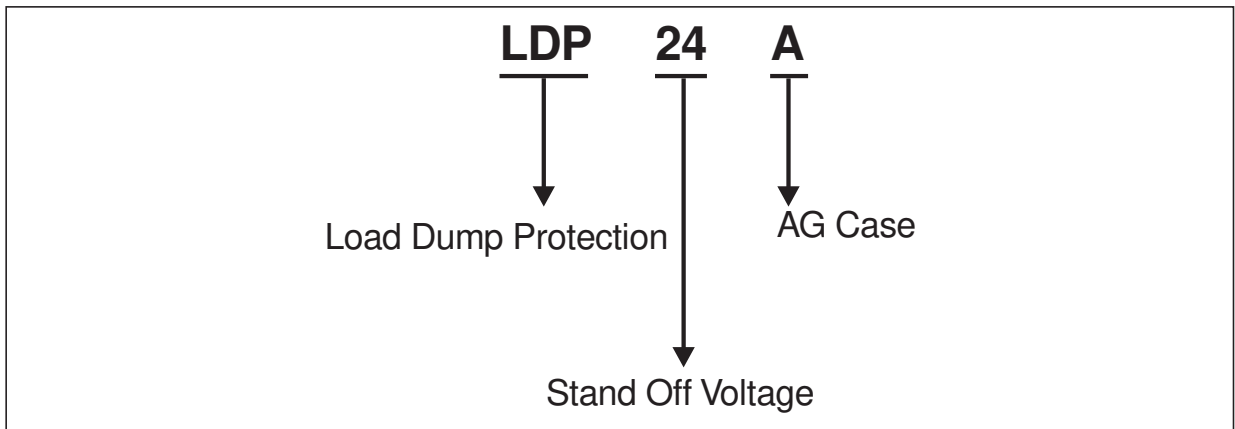


Fig. 8: Junction capacitance versus reverse applied voltage.

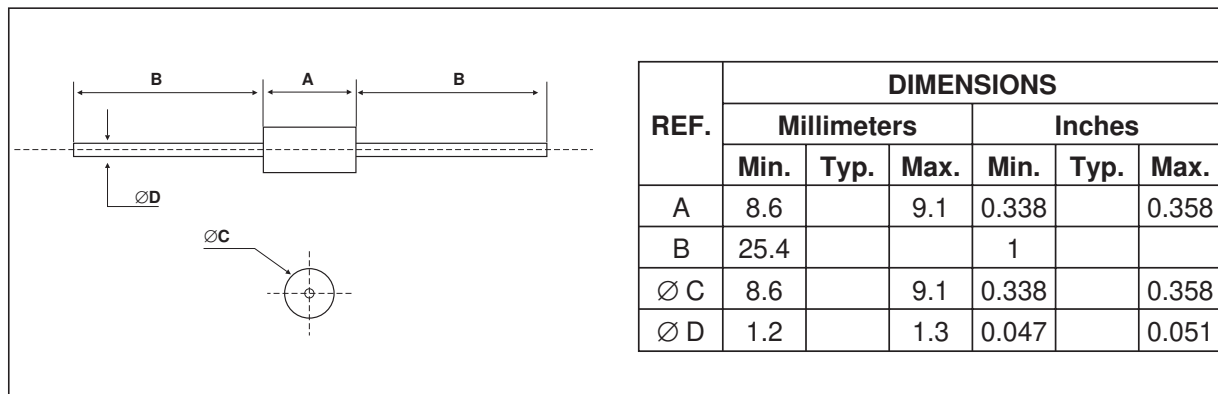


ORDER CODE



PACKAGE MECHANICAL DATA

R6 (Plastic)



Type	Marking	Package	Weight	Base qty	Delivery mode
LDP24A	LDP24A	R6	2.048 g	100	Ammopack
LDP24ARL	LDP24A	R6	2.048 g	1000	Tape & Reel

- Resin meets UL94-V0

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